

MultiBond

Innerlayer Bonding System

The No-Risk Oxide Alternative From The Market Leader In Innerlayer Bonding

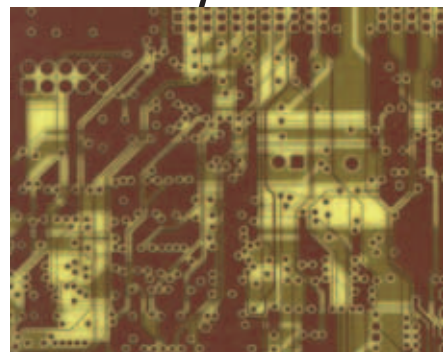
MacDermid MultiBond is the leading technology for innerlayer adhesion promotion designed specifically to perform at the high temperatures required for today's lead-free soldering of circuit boards. An exceptional alternative to oxide whose chemistry is compatible with all existing equipment, MultiBond is supported by MacDermid's renowned on-site service.

MultiBond, trusted by over 250 customers worldwide, now offers a next-generation innerlayer bonding process with significantly higher copper capacity and sludge-free operation. Able to withstand the intense thermal stress that results from lead-free processing, it improves performance on controlled impedance designs and reduces waste treatment and machine maintenance costs. As part of our on-going program of innovation in oxide alternative technology, the MultiBond family is the right choice for critical multilayer applications.

For the industry's leading innerlayer bonding system that improves performance while reducing overall costs, count on the company that says "Yes We Can." MacDermid.

Key Features

- Optimum adhesion promoter for bonding multilayer circuit boards
- Installed base of over 250 customers worldwide
- Exceptional precision for controlled impedance work
- Higher copper-carrying capacity results in less solid waste
- Best results on advanced dielectrics
- Compatible with existing equipment



YES WE CANSM

 **MacDermid**
Electronics Solutions

MultiBond

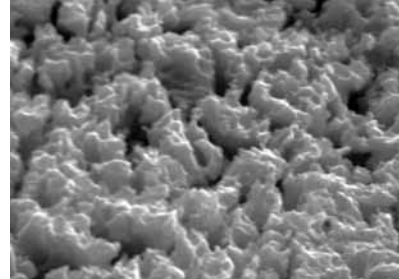
Innerlayer Bonding System

Superior Bonding for Multilayer Adhesion

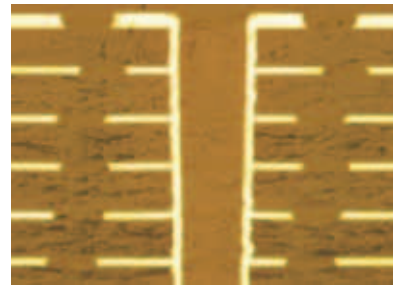
As the market leader in alternative oxide, MacDermid has designed the best coating chemistry for your application. MultiBond enables consistently high bond strengths to high Tg epoxy, PTFE, polyimide, BT, and non-halogenated resins. And our technical experts can help you make a seamless transition to lead-free assembly.

Special features of our latest generation chemistry include lower etch for controlled impedance, minimal wedge attack, high copper loading (>40 grams/liter) and clean, sludge-free processing.

Able to increase productivity while reducing overall costs, MultiBond is the right choice in oxide alternative.



Typical SEM at 5000x of MultiBond surface showing superior topography for bonding to resin prepregs.



4x sequential lamination multilayer subsequently processed through 3x lead-free reflow and soldershocked 3x @ 260°C for assembly rework simulation. No delamination.

YES WE CANSM

It takes more than innovative, high performance products and superior technical service to help our customers compete and win in today's global marketplace. It takes a total commitment to understanding their needs and the ability to provide the right solutions—every time.

When success is your only goal, trust the company that says "Yes We Can."

 **MacDermid**
Electronics Solutions

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